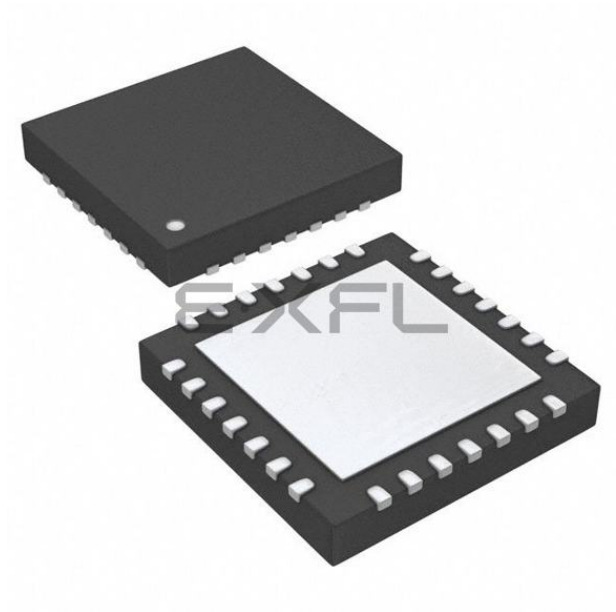
Microchip Technology - DSPIC33FJ16MC102T-I/ML Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16mc102t-i-ml

4.2 Data Address Space

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family CPU has a separate 16-bit-wide data memory space. The data space is accessed using separate Address Generation Units (AGUs) for read and write operations. The data memory maps is shown in Figure 4-4.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the data space. This arrangement gives a data space address range of 64 Kbytes or 32K words. The lower half of the data memory space (that is, when EA<15> = 0) is used for implemented memory addresses, while the upper half (EA<15> = 1) is reserved for the Program Space Visibility area (see **Section 4.6.3 "Reading Data from Program Memory Using Program Space Visibility"**).

Microchip dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices implement up to 2 Kbytes of data memory. Should an EA point to a location outside of this area, an all-zero word or byte will be returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte-addressable, 16-bit wide blocks. Data is aligned in data memory and registers as 16-bit words, but all data space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® MCU devices and improve data space memory usage efficiency, the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family instruction set supports both word and byte operations. As a consequence of byte accessibility, all Effective Address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] will result in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

Data byte reads will read the complete word that contains the byte, using the LSB of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, data memory and registers are organized as two parallel byte-wide entities with shared (word) address decoding but separate write lines. Data byte writes only write to the corresponding side of the array or register that matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction in progress is completed. If the error occurred on a write, the instruction is executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user application to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB. The MSB is not modified.

A Sign-Extend (SE) instruction is provided to allow user applications to translate 8-bit signed data to 16-bit signed values. Alternately, for 16-bit unsigned data, user applications can clear the MSB of any W register by executing a Zero-Extend (ZE) instruction on the appropriate address.

4.2.3 SFR SPACE

The first 2 Kbytes of the Near Data Space, from 0x0000 to 0x07FF, is primarily occupied by Special Function Registers (SFRs). These are used by the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'.

Note:	The actual set of peripheral features and interrupts varies by the device. Refer to the corresponding device tables and pinout diagrams for device-specific information.

4.2.4 NEAR DATA SPACE

The 8-Kbyte area, between 0x0000 and 0x1FFF, is referred to as the Near Data Space. Locations in this space are directly addressable via a 13-bit absolute address field within all memory direct instructions. Additionally, the whole data space is addressable using the MOV class of instructions, which support Memory Direct Addressing mode with a 16-bit address field or by using Indirect Addressing mode with a Working register as an Address Pointer.

TABLE 4-12: I2C1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
I2C1RCV	0200	—	—	—	—	—	—	—	—	I2C1 Receive Register								0000
I2C1TRN	0202	—	—	—	—	—	—	—	—	I2C1 Transmit Register								00FF
I2C1BRG	0204	—	—	—	—	—	—	—	Baud Rate Generator Register									0000
I2C1CON	0206	I2CEN	—	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
I2C1STAT	0208	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
I2C1ADD	020A	—	—	—	—	—	—	I2C1 Address Register										0000
I2C1MSK	020C	—	—	—	—	—	—	I2C1 Address Mask Register										0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-13: UART1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
U1MODE	0220	UARTEN	—	USIDL	IREN	RTSMD	—	UEN1	UEN0	WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSEL1	PDSEL0	STSEL	0000
U1STA	0222	UTXISEL1	UTXINV	UTXISEL0	—	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL1	URXISEL0	ADDEN	RIDLE	PERR	FERR	OERR	URXDA	0110
U1TXREG	0224	—	—	—	—	—	—	—	UART1 Transmit Register									xxxx
U1RXREG	0226	—	—	—	—	—	—	—	UART1 Receive Register									0000
U1BRG	0228	Baud Rate Generator Prescaler																0000

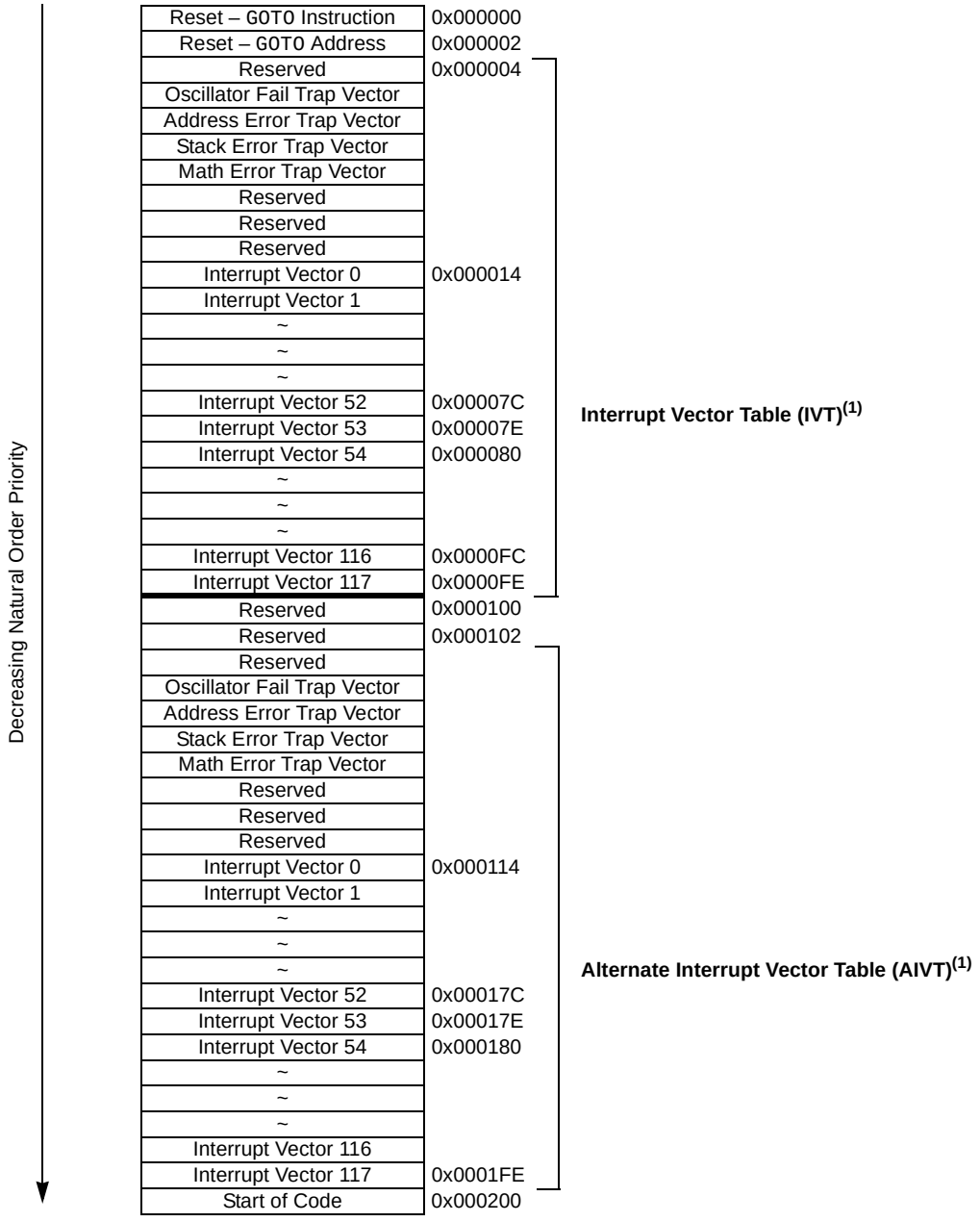
Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-14: SPI1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
SPI1STAT	0240	SPIEN	—	SPISIDL	—	—	—	—	—	—	SPIROV	—	—	—	—	SPITBF	SPIRBF	0000
SPI1CON1	0242	—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE	SSEN	CKP	MSTEN	SPRE2	SPRE1	SPRE0	PPRE1	PPRE0	0000
SPI1CON2	0244	FRMEN	SPIFSD	FRMPOL	—	—	—	—	—	—	—	—	—	—	—	FRMDLY	—	0000
SPI1BUF	0248	SPI1 Transmit and Receive Buffer Register																0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

FIGURE 7-1: dsPIC33FJ16(GP/MC)101/102 AND dsPIC33FJ32(GP/MC)101/102/104 INTERRUPT VECTOR TABLE



Note 1: See Table 7-1 for the list of implemented interrupt vectors.

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR	DIV0ERR	—	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A

bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B

bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A

bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B

bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit
1 = Trap overflow of Accumulator A
0 = Trap is disabled

bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit
1 = Trap overflow of Accumulator B
0 = Trap is disabled

bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit
1 = Trap on catastrophic overflow of Accumulator A or B is enabled
0 = Trap is disabled

bit 7 **SFTACERR:** Shift Accumulator Error Status bit
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift

bit 6 **DIV0ERR:** Arithmetic Error Status bit
1 = Math error trap was caused by a divide-by-zero
0 = Math error trap was not caused by a divide-by-zero

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **MATHERR:** Arithmetic Error Status bit
1 = Math error trap has occurred
0 = Math error trap has not occurred

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER(1) (CONTINUED)

bit 3 **CF:** Clock Fail Detect bit (read/clear by application)
1 = FSCM has detected a clock failure
0 = FSCM has not detected a clock failure

bit 2 **Unimplemented:** Read as '0'

bit 1 **LPOSCEN:** Secondary (LP) Oscillator Enable bit
1 = Enables secondary oscillator
0 = Disables secondary oscillator

bit 0 **OSWEN:** Oscillator Switch Enable bit
1 = Requests oscillator switch to selection specified by the NOSC<2:0> bits
0 = Oscillator switch is complete

Note 1: Writes to this register require an unlock sequence. Refer to **"Oscillator (Part VI)"** (DS70644) in the *"dsPIC33/PIC24 Family Reference Manual"* for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transitional clock source between the two PLL modes.

10.5 I/O Helpful Tips

1. In some cases, certain pins, as defined in **Section 26.0 "Electrical Characteristics"**, Table 26-11 under "Injection Current", have internal protection diodes to VDD and VSS. The term, "Injection Current", is also referred to as "Clamp Current". On designated pins, with sufficient external current limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings with nominal VDD, with respect to the VSS and VDD supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes, that the resulting current being injected into the device, that is clamped internally by the VDD and VSS power rails, may affect the ADC accuracy by four to six counts.
2. I/O pins that are shared with any analog input pin, (i.e., ANx), are always analog pins by default after any Reset. Consequently, any pin(s) configured as an analog input pin, automatically disables the digital input pin buffer. As such, any attempt to read a digital input pin will always return a '0' regardless of the digital logic level on the pin if the analog pin is configured. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the ADC1 Port Configuration Low (AD1PCFGL) register in the ADC module, by setting the appropriate bit that corresponds to that I/O port pin, to a '1'. On devices with more than one ADC, both analog pin configurations for both ADC modules must be configured as a digital I/O pin for that pin to function as a digital I/O pin.

Note:	Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0x0, while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.

3. Most I/O pins have multiple functions. Referring to the device pin diagrams in the data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name from left-to-right. The left most function name takes precedence over any function to its right in the naming convention. For example: AN16/T2CK/T7CK/RC1. This indicates that AN16 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.
4. Each CN pin has a configurable internal weak pull-up resistor. The pull-ups act as a current source connected to the pin and eliminates the need for external resistors in certain applications. The internal pull-up is to ~(VDD – 0.8), not VDD. This is still above the minimum VIH of CMOS and TTL devices.
5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the VOH/IOH and VOL/IOL DC characteristic specification. The respective IOH and IOL current rating only applies to maintaining the corresponding output at or above the VOH and at or below the VOL levels. However, for LEDs unlike digital inputs of an externally connected device, they are not governed by the same minimum VIH/VIL levels. An I/O pin output can safely sink or source any current less than that listed in the absolute maximum rating section of the data sheet. For example:

   VOH = 2.4v @ IOH = -6 mA and VDD = 3.3V

   The maximum output current sourced by any 6 mA I/O pin = 15 mA.

   LED source current < 15 mA is technically permitted. Refer to the VOH/IOH specifications in **Section 26.0 "Electrical Characteristics"** for additional information.

10.6 I/O Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en554109

10.6.1 KEY RESOURCES

- **"I/O Ports"** (DS70193) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 12-4: T5CON: TIMER5 CONTROL REGISTER(1)

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON(3)	—	TSIDL(2)	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	U-0
—	TGATE(3)	TCKPS1(3)	TCKPS0(3)	—	—	TCS(3)	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TON:** Timer5 On bit(3)
1 = Starts 16-bit Timer3
0 = Stops 16-bit Timer3

bit 14 **Unimplemented:** Read as '0'

bit 13 **TSIDL:** Timer5 Stop in Idle Mode bit(2)
1 = Discontinues timer operation when device enters Idle mode
0 = Continues timer operation in Idle mode

bit 12-7 **Unimplemented:** Read as '0'

bit 6 **TGATE:** Timer5 Gated Time Accumulation Enable bit(3)
When TCS = 1:
This bit is ignored.
When TCS = 0:
1 = Gated time accumulation is enabled
0 = Gated time accumulation is disabled

bit 5-4 **TCKPS<1:0>:** Timer5 Input Clock Prescale Select bits(3)
11 = 1:256 prescale value
10 = 1:64 prescale value
01 = 1:8 prescale value
00 = 1:1 prescale value

bit 3-2 **Unimplemented:** Read as '0'

bit 1 **TCS:** Timer5 Clock Source Select bit(3)
1 = External clock from T5CK pin
0 = Internal clock (FOSC/2)

bit 0 **Unimplemented:** Read as '0'

Note 1: This register is available in dsPIC33FJ32(GP/MC)10X devices only.

2: When 32-bit timer operation is enabled (T32 = 1) in the Timer4 Control register (T4CON<3>), the TSIDL bit must be cleared to operate the 32-bit timer in Idle mode.

3: When the 32-bit timer operation is enabled (T32 = 1) in the Timer4 Control register (T4CON<3>), these bits have no effect.

17.3 I²C Control Registers

REGISTER 17-1: I2CxCON: I2Cx CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-1, HC	R/W-0	R/W-0	R/W-0	R/W-0
I2CEN	—	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC
GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **I2CEN:** I2Cx Enable bit
1 = Enables the I2Cx module, and configures the SDAx and SCLx pins as serial port pins
0 = Disables the I2Cx module; all I²C™ pins are controlled by port functions

bit 14 **Unimplemented:** Read as '0'

bit 13 **I2CSIDL:** I2Cx Stop in Idle Mode bit
1 = Discontinues module operation when device enters an Idle mode
0 = Continues module operation in Idle mode

bit 12 **SCLREL:** SCLx Release Control bit (when operating as I²C slave)
1 = Releases SCLx clock
0 = Holds SCLx clock low (clock stretch)
If STREN = 1:
Bit is R/W (i.e., software can write '0' to initiate stretch and write '1' to release clock). Hardware clears at beginning of every slave data byte transmission. Hardware clears at end of every slave address byte reception. Hardware clears at every slave data byte reception.
If STREN = 0:
Bit is R/S (i.e., software can only write '1' to release clock). Hardware clears at beginning of every slave data byte transmission. Hardware clears at end of every slave address byte reception.

bit 11 **IPMIEN:** Intelligent Peripheral Management Interface (IPMI) Enable bit
1 = IPMI mode is enabled; all addresses are Acknowledged
0 = IPMI mode is disabled

bit 10 **A10M:** I2Cx 10-Bit Slave Address bit
1 = I2CxADD is a 10-bit slave address
0 = I2CxADD is a 7-bit slave address

bit 9 **DISSLW:** Disable Slew Rate Control bit
1 = Slew rate control is disabled
0 = Slew rate control is enabled

bit 8 **SMEN:** SMBus Input Levels bit
1 = Enables I/O pin thresholds compliant with SMBus specification
0 = Disables SMBus input thresholds

bit 7 **GCEN:** General Call Enable bit (when operating as I²C slave)
1 = Enables interrupt when a general call address is received in the I2CxRSR (module is enabled for reception)
0 = General call address is disabled

REGISTER 19-6: AD1CSSL: ADC1 INPUT SCAN SELECT REGISTER LOW(1,2,3)

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS15(4)	—	—	CSS<12:8>(4,6)				
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS<7:0>(4,5)							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CSS15:** ADC1 Input Scan Selection bit(4)
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 14-13 **Unimplemented:** Read as '0'

bit 12-0 **CSS<12:0>:** ADC1 Input Scan Selection bits(4,5,6)
1 = Selects ANx for input scan
0 = Skips ANx for input scan

Note 1: On devices without 14 analog inputs, all AD1CSSL bits can be selected by the user application. However, inputs selected for scan without a corresponding input on the device converts VREFL.

2: CSSx = ANx, where x = 0 through 12 and 15.

3: CTMU temperature sensor input cannot be scanned.

4: The CSS<15,12:11,8:6> bits are available in the dsPIC33FJ32(GP/MC)104 devices only and are reserved in all other devices.

5: The CSS<5:4> bits are available on all devices, excluding the dsPIC33FJXX(GP/MC)101 devices, where they are reserved.

6: The CSS<10:9> bits are available on all devices, excluding the dsPIC33FJ16(GP/MC)101/102 devices, where they are reserved.

REGISTER 21-6: RTCVAL (WHEN RTCPTR<1:0> = 01): RTCC WEEKDAY AND HOURS VALUE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	—	—	—	—	WDAY2	WDAY1	WDAY0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	HRTEN1	HRTEN0	HRONE3	HRONE2	HRONE1	HRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10-8 **WDAY<2:0>:** Binary Coded Decimal Value of Weekday Digit bits
Contains a value from 0 to 6.

bit 7-6 **Unimplemented:** Read as '0'

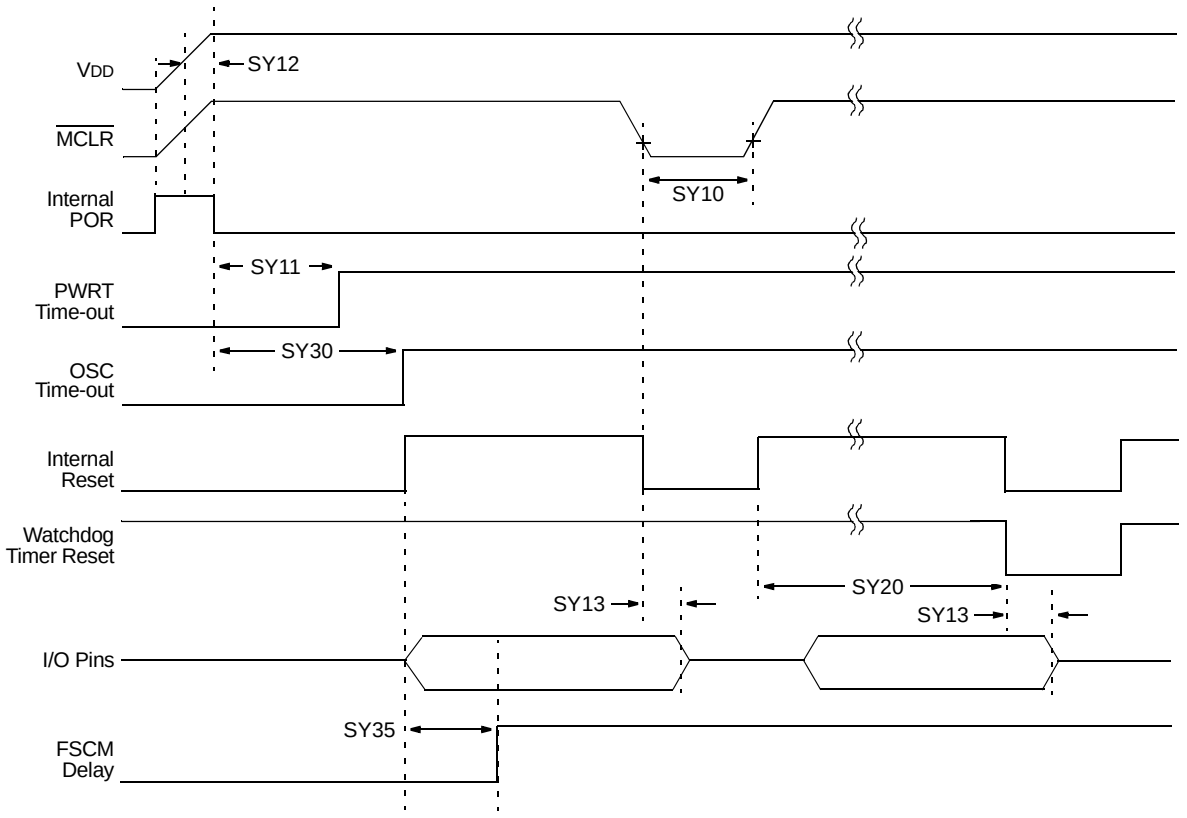
bit 5-4 **HRTEN<1:0>:** Binary Coded Decimal Value of Hour's Tens Digit bits
Contains a value from 0 to 2.

bit 3-0 **HRONE<3:0>:** Binary Coded Decimal Value of Hour's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

NOTES:

FIGURE 26-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

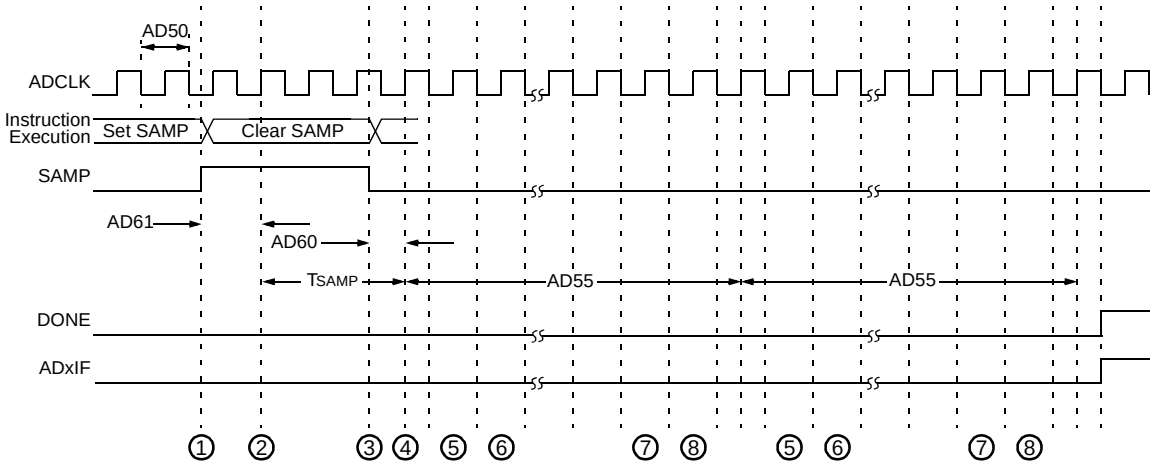
TABLE 26-21: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symb**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SY10	TMCL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	µs	
SY11	TPWRT	Power-up Timer Period	—	64	—	ms	
SY12	TPOR	Power-on Reset Delay	3	10	30	µs	
SY13	TIOZ	I/O High-Impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	—	1.2	µs	
SY20	TWDT1	Watchdog Timer Time-out Period	—	—	—	ms	See **Section 23.4 "Watchdog Timer (WDT)"** and LPRC Parameter F21a (Table 26-19).
SY30	TOST	Oscillator Start-up Time	—	1024 * TOSC	—	—	TOSC = OSC1 period
SY35	TFSCM	Fail-Safe Clock Monitor Delay	—	500	900	µs	

Note 1: These parameters are characterized but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

FIGURE 26-31: ADC CONVERSION TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000)



1 – Software sets ADxCON. SAMP to start sampling.

2 – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70183) in the "*dsPIC33/PIC24 Family Reference Manual*".

3 – Software clears ADxCON. SAMP to start conversion.

4 – Sampling ends, conversion sequence starts.

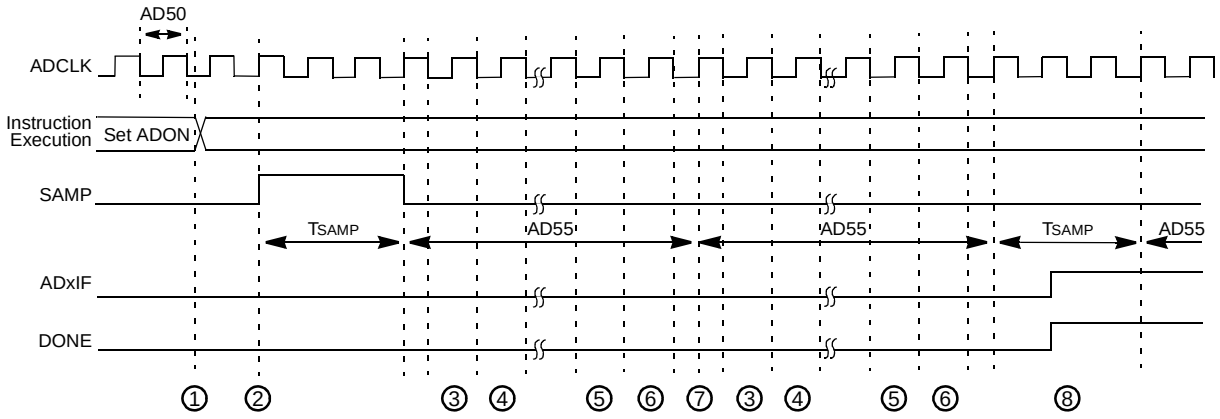
5 – Convert bit 9.

6 – Convert bit 8.

7 – Convert bit 0.

8 – One TAD for end of conversion.

FIGURE 26-32: ADC CONVERSION TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



1 – Software sets ADxCON. ADON to start AD operation.

2 – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33/PIC24 Family Reference Manual"*.

3 – Convert bit 9.

4 – Convert bit 8.

5 – Convert bit 0.

6 – One TAD for end of conversion.

7 – Begin conversion of next channel.

8 – Sample for time specified by SAMC<4:0>.

TABLE 26-49: 10-BIT ADC CONVERSION TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ(1)**	**Max.**	**Units**	**Conditions**
Clock Parameters(2)							
AD50	TAD	ADC Clock Period	76	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period	—	250	—	ns	
Conversion Rates							
AD55	tCONV	Conversion Time	—	12 TAD	—	—	
AD56	FCNV	Throughput Rate	—	—	1.1	Msps	
AD57	TSAMP	Sample Time	2.0 TAD	—	—	—	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger(1)	2.0 TAD	—	3.0 TAD	—	Auto-Convert Trigger (SSRC<2:0> = 111) not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit(1)	2.0 TAD	—	3.0 TAD	—	
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1)(1)	—	0.5 TAD	—	—	
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(1)	—	—	20	μs	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

TABLE 26-53: COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions:3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
VRD310	CVRES	Resolution	CVRSRC/24	—	CVRSRC/32	LSb	
VRD311	CVRAA	Absolute Accuracy	—	—	0.5	LSb	
VRD312	CVRUR	Unit Resistor Value (R)	—	2k	—	Ω	

TABLE 26-54: CTMU CURRENT SOURCE SPECIFICATIONS

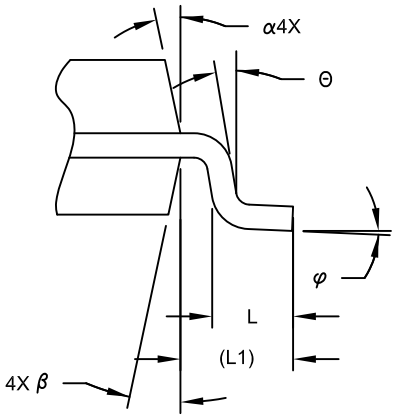
DC CHARACTERISTICS			Standard Operating Conditions:3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
CTMU Current Source							
CTMUI1	IOUT1	Base Range(1)	320	550	980	na	IRNG<1:0> bits (CTMUICON<9:8>) = 0b01
CTMUI2	IOUT2	10x Range(1)	3.2	5.5	9.8	µA	IRNG<1:0> bits (CTMUICON<9:8>) = 0b10
CTMUI3	IOUT3	100x Range(1)	32	55	98	µA	IRNG<1:0> bits (CTMUICON<9:8>) = 0b11
Internal Diode							
CTMUFV1	VF	Forward Voltage(2)	—	0.77	—	V	IRNG<1:0> bits (CTMUICON<9:8>) = 0b11 @ +25°C
CTMUFV2	VFVR	Forward Voltage Rate(2)	—	-1.38	—	mV/ºC	IRNG<1:0> bits (CTMUICON<9:8>) = 0b11

Note 1: Nominal value at center point of current trim range (ITRIM<5:0> bits (CTMUICON<15:10>) = 0b000000).

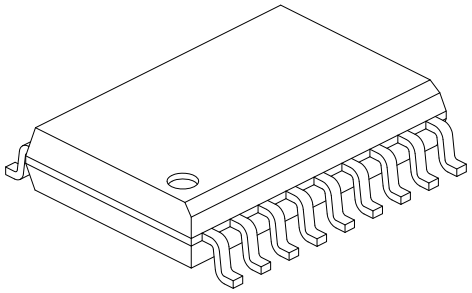
2: ADC module configured for conversion speed of 500 ksps. Parameters are characterized but not tested in manufacturing.

18-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		18	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		11.55 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

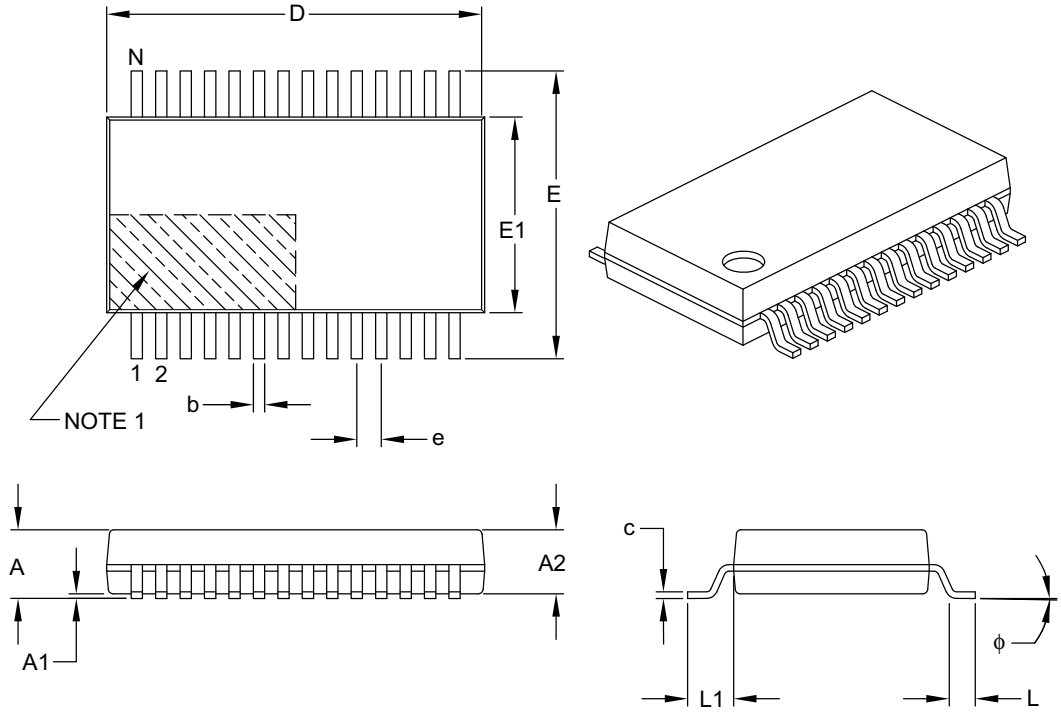
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-051C Sheet 2 of 2

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

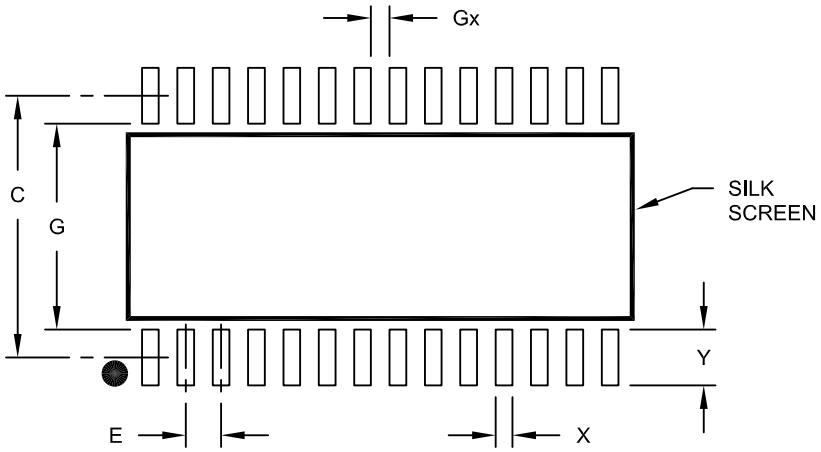
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

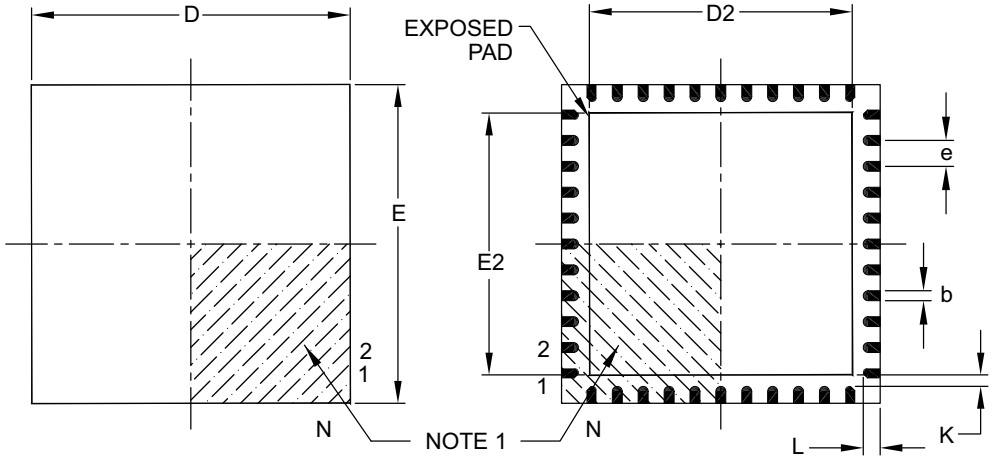
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

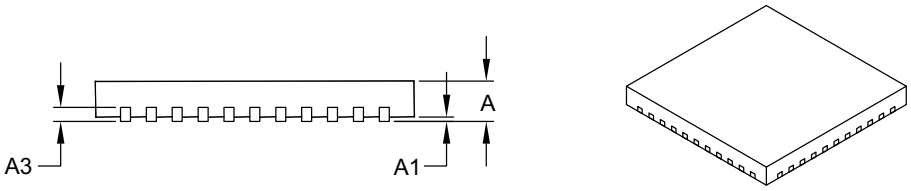
Microchip Technology Drawing No. C04-2052A

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW **BOTTOM VIEW**



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.30	6.45	6.80
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.30	6.45	6.80
Contact Width	b	0.25	0.30	0.38
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

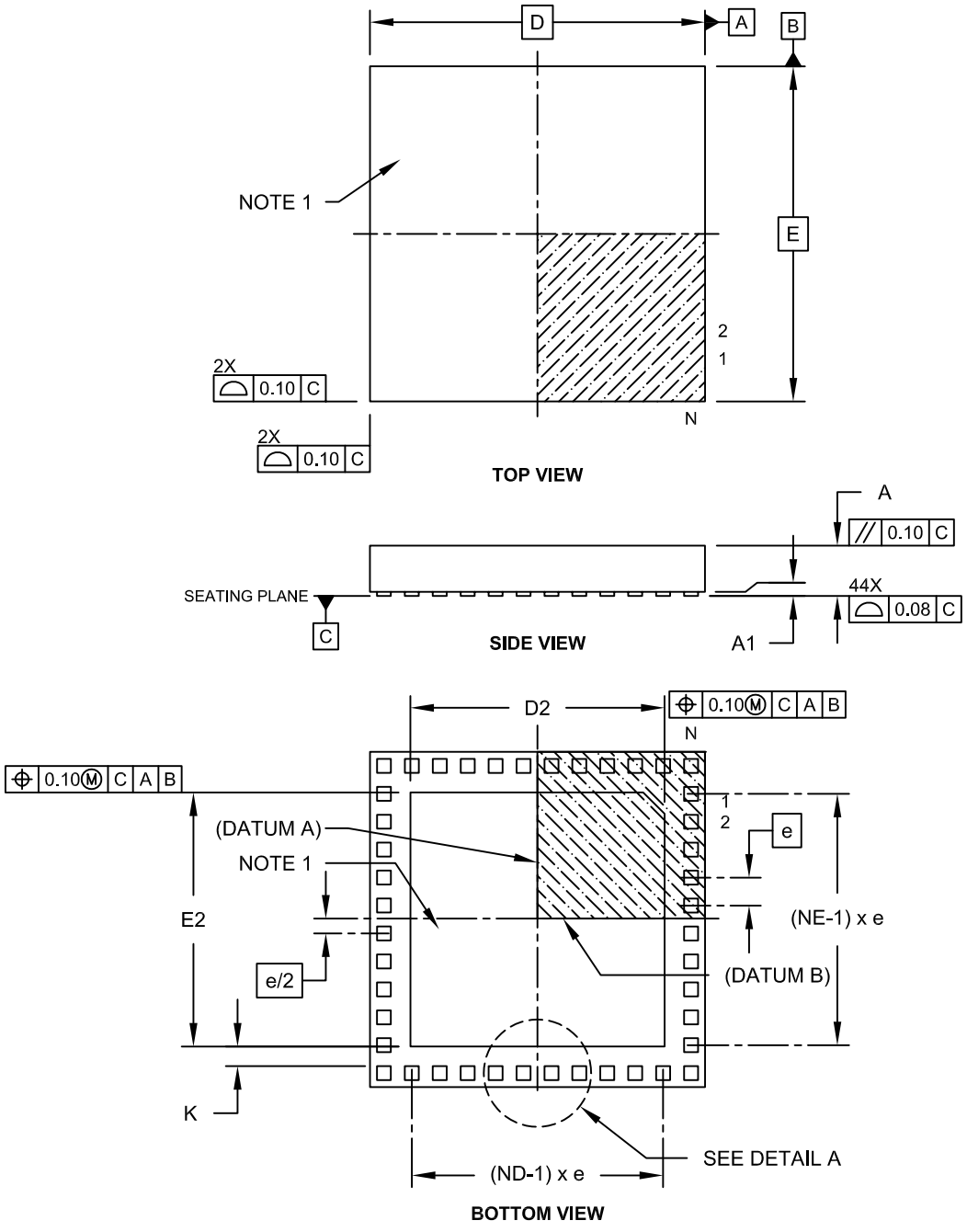
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-157C Sheet 1 of 2